

Halogen-Free/High Tg/Low CTE/High Reliability

特性 (Feature)

- 无卤, 无锑, 无红磷
Halogen, antimony and red phosphorous free
- 优良的耐热性与耐CAF性
Excellent thermal reliability and Anti-CAF
- 超低的Z轴热膨胀系数
Extremely low Z-CTE
- 优秀的尺寸稳定性
Excellent Dimensional stability.

应用 (Application)

- 智能手机, 笔记本电脑, 平板电脑
Smartphone, NB, Tablet,
- 汽车电子
Automotive electronics
- 无线通信设施
Wireless communication infrastructure
- 服务器
Servers

板材性能 (Laminate Properties)

Test Item 测试项目	Test Method (IPC-TM- 650) 测试方法	Test Condition 处理条件	Unit 单位	Typical Value 典型值		
Thermal 热性能	Thermal Stress 热应力	2.4.13.1	Float 288 °C / Unetched	Sec	≥360	
	Glass Transition (Tg) 玻璃化转变温度	2.4.25	DSC	°C	175	
		2.4.24.4	DMA		195	
	CTE / Z-Axis Expansion Z-轴热膨胀系数	2.4.24	Alpha 1	ppm/°C	35	
			Alpha 2		180	
			50 - 260 °C	%	2.0	
	X/Y CTE X/Y-轴热膨胀系数	2.4.24	40 °C - 125 °C	ppm/°C	12/13	
	T-260	2.4.24.1	TMA	min	>60	
T-288	2.4.24.1	TMA	min	>60		
TD(5% weight loss) Flammability 燃烧性	2.4.24.6 UL94	TGA E-24/125	°C Rating	390 V-0		
Electrical 电性能	Surface Resistivity 表面电阻率	2.5.17.1	C-96/35/90	MΩ	5.0×10 ⁸	
	Volume Resistivity 体积电阻率	2.5.17.1	C-96/35/90	MΩ-cm	6.2×10 ⁹	
	Dielectric Breakdown 击穿电压	2.5.6	D-48/50+D0.5/23	kV	≥45	
	Dielectric Constant/ Loss Tangent 介电常数/介质损耗	IEC61189-2-721	Etched (RC50%)	@ 1 GHz	—	4.4/0.0069
				@ 10 GHz		4.4/0.0098
			Etched (RC70%)	@ 1 GHz	—	3.74/0.0072
				@ 10 GHz		3.56/0.0101
CTI 相对漏电起痕指数	IEC60112	Etched/0.1% NH ₄ CL	V	≥200		
Arc Resistance 耐电弧性	2.5.1	D-48/50+D-0.5/23	Sec	124		
Mechanical 机械性能	Peel Strength (1 oz.) 铜箔剥离强度	2.4.8	A	N/mm	--	
			Float 288 °C / 10 Sec		1.05	
	Flexural Strength 弯曲强度	2.4.4	Lengthwise	N/mm ²	600	
Crosswise			530			
Water Absorption 吸水率	2.6.2.1	D-24/23	%	0.09		

Remarks:

- Typical Values for reference only.
- Standard Values according to IPC-4101E/127/128/130
- Typical Value of Specimen thickness is 1.2mm (#2116*10)

注:

- 典型值只供参考
- 规格值参照 IPC-4101E/127/128/130
- 样品的厚度为 1.2mm (#2116*10)

